SPEED SPREAD Electronic Materials Co., Ltd.

APPLICATION FOR

POWER SUPPLY

COMPANY PROFILE

The company is located in Qiaotou Town, Dongguan City, Guangdong Province, China and has 10000 square courtyard in the workshop, obtain qualification certificates: ISO9001, ISO140001, IATF16949, UL, high-tech enterprises. We have a professional R&D team to meet the diverse needs of customers, as well as professional instruments including materials/thermal/electrical properties/reliability testing equipment to ensure product quality.

Form of Power Supply

- Switching Power Supply
- Open-Frame Power Supply
- PCB Form

- Linear Power Supply
- Cuboid

- Modular Power Supply
- Box/Enclosed Type

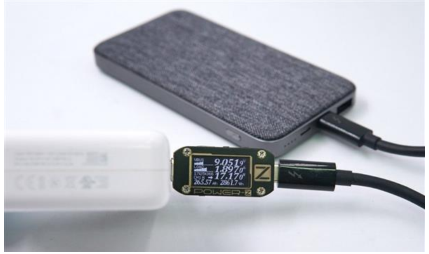
- Rechargeable Battery/Power Supply
- Cylindrical/Flat Rectangle

- Switching Power Supply
- Enclosed Power Supply
- Cuboid

Ultra-Slim Power Supply

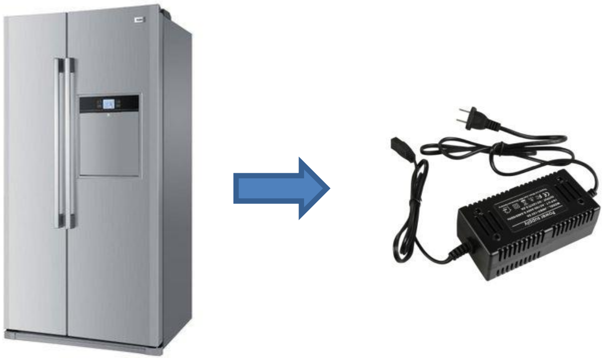
DIN Rail Power Supply

- Rectangular

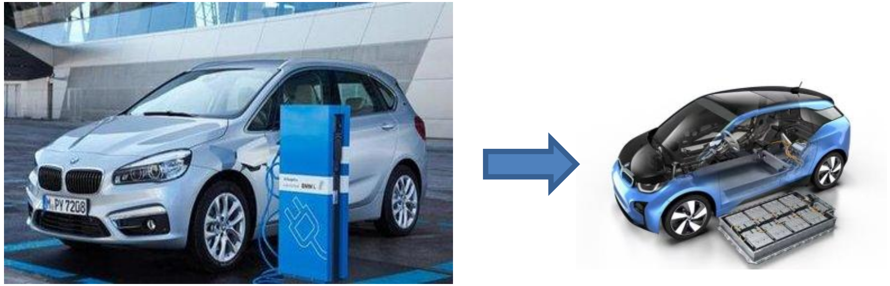


USB PD Power Supply

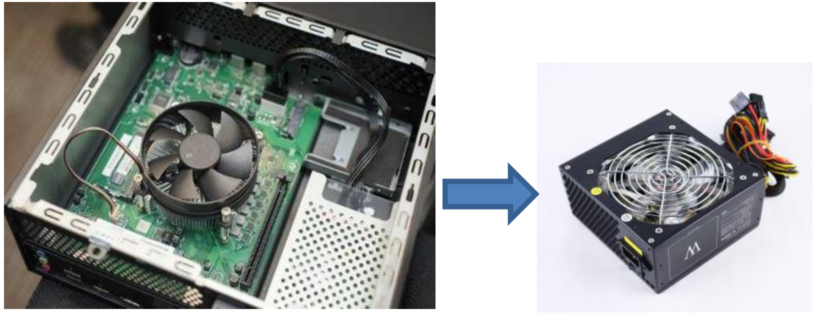
Power Supply Application Scenario



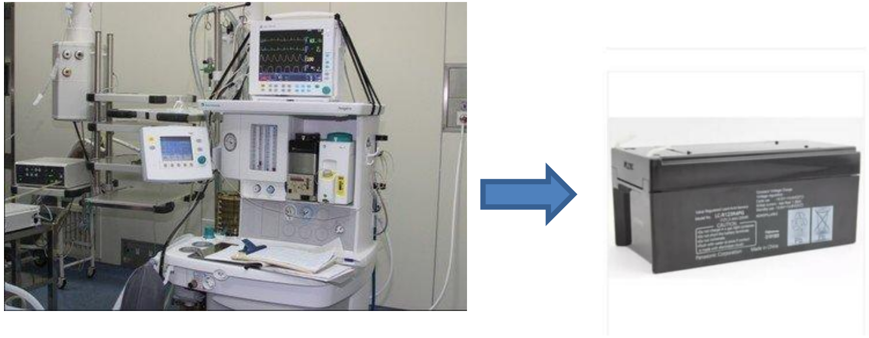
Refrigerator



Automobile

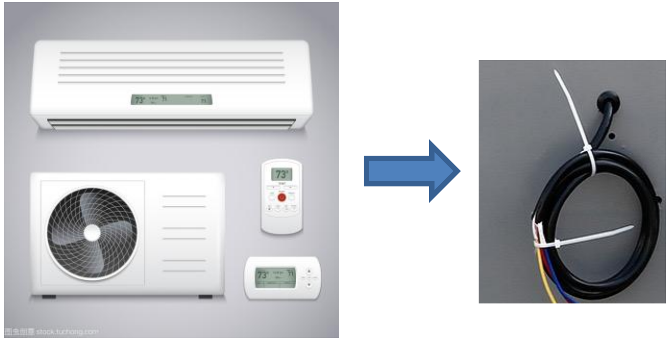


Computer Case



Medical Equipment

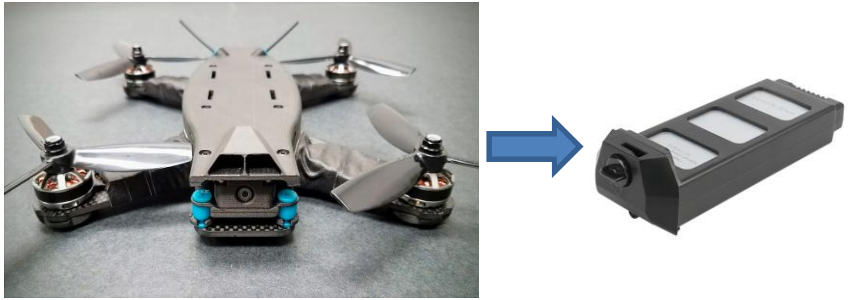
Power Supply Application Scenario



Air Conditioner

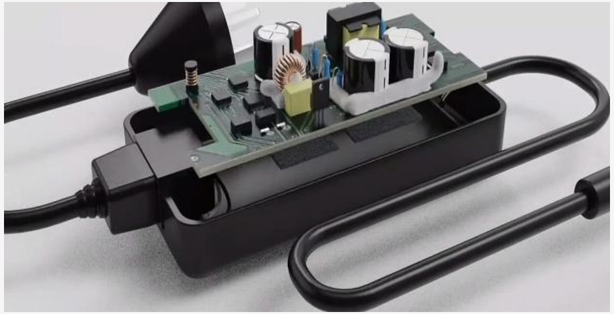
LED Floodlight

CNC Machine

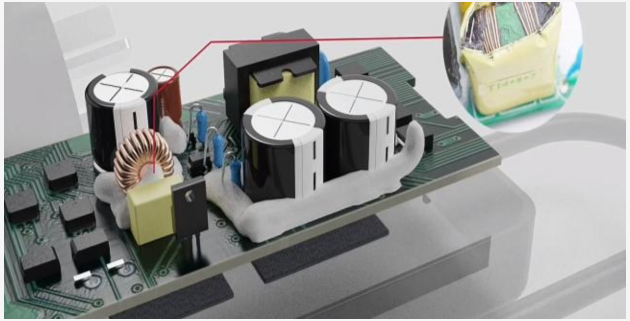


UAV

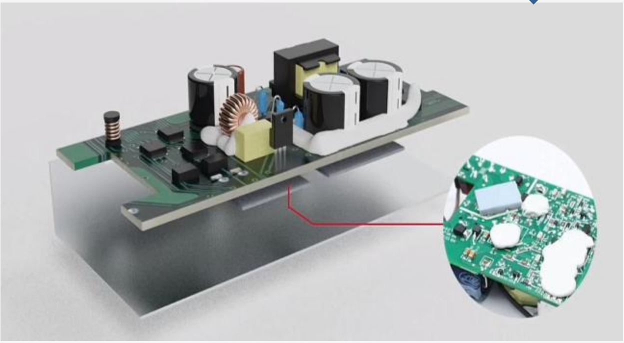
Power Adapter



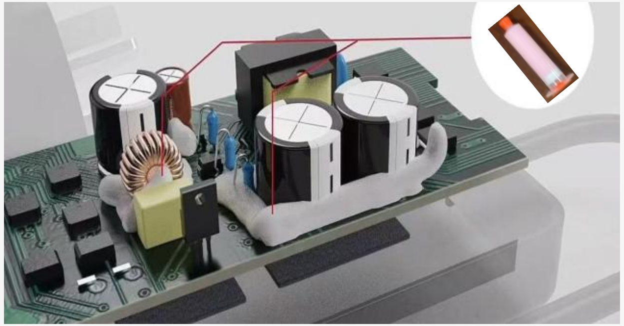
Power Adapter



Partial or complete potting with Thermally Conductive Potting Compound.



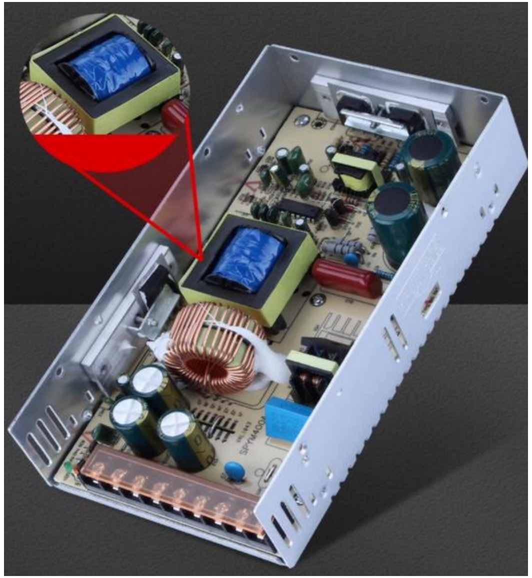
Apply Thermal Insulation Pads or Thermal Paste on the backside of the PCB.



At the Electronic Components, we use Thermally Conductive Pad Adhesive for heat transfer, bonding, and fixation.

Power Supply Apparatus

PCBA Application Scenarios	Heat Dissipation Material
MOSFET/IGBT/Diodes	Thermal Insulation Pad /Thermal Paste
Transformers/Inductors	Flexible Thermal Pad/Thermally Conductive Adhesive
Control ICs/PCB Hotspots	Thin Thermal Pad/Metal Core PCB
Enclosure-PCB Heat Dissipation	Phase Change Material/Thermal Conductive Double-Sided Tape
High-Vibration Environments	Elastic Thermal Gel
High-Voltage Isolation	Ceramic-Filled Thermal Pad



Power Box

PCBA Application Scenarios	Heat Dissipation Material
Power Semiconductors	Thermal Insulation Pad /Thermal Paste
Transformers/Inductors	Flexible Graphite Pad/Thermally Conductive Adhesive
Control ICs/PCB Hotspots	Thin Thermal Pad/Metal Core PCB
Enclosure & PCB Thermal Management	Phase Change Material/Thermal Conductive Double-Sided Tape
High-Vibration Environments	Elastic Thermal Gel
High-Voltage Isolation	Ceramic-Filled Thermal Pad

Thank You!

Speed Spread Electronic Materials Co.,Ltd.

SPEED SPREAD

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